


NO.	ECO #	REVISIONS	DATE BY
0	005244	NEW RELEASE	5/7/98 BPP
		CHANGED WIRE COLORS ON P4	5/28/98 BPP
		CHANGE TITLE FROM CC46 TO MC16	3/2/00 BPP
		PROJECT #99002	
1	006263	CHANGE RAW PCB TO 08270120	10/24/00 BPP
02	006456	ADD U2 SOCKET, NEW PROG, NEW PCB LABEL	06/12/01 SJS



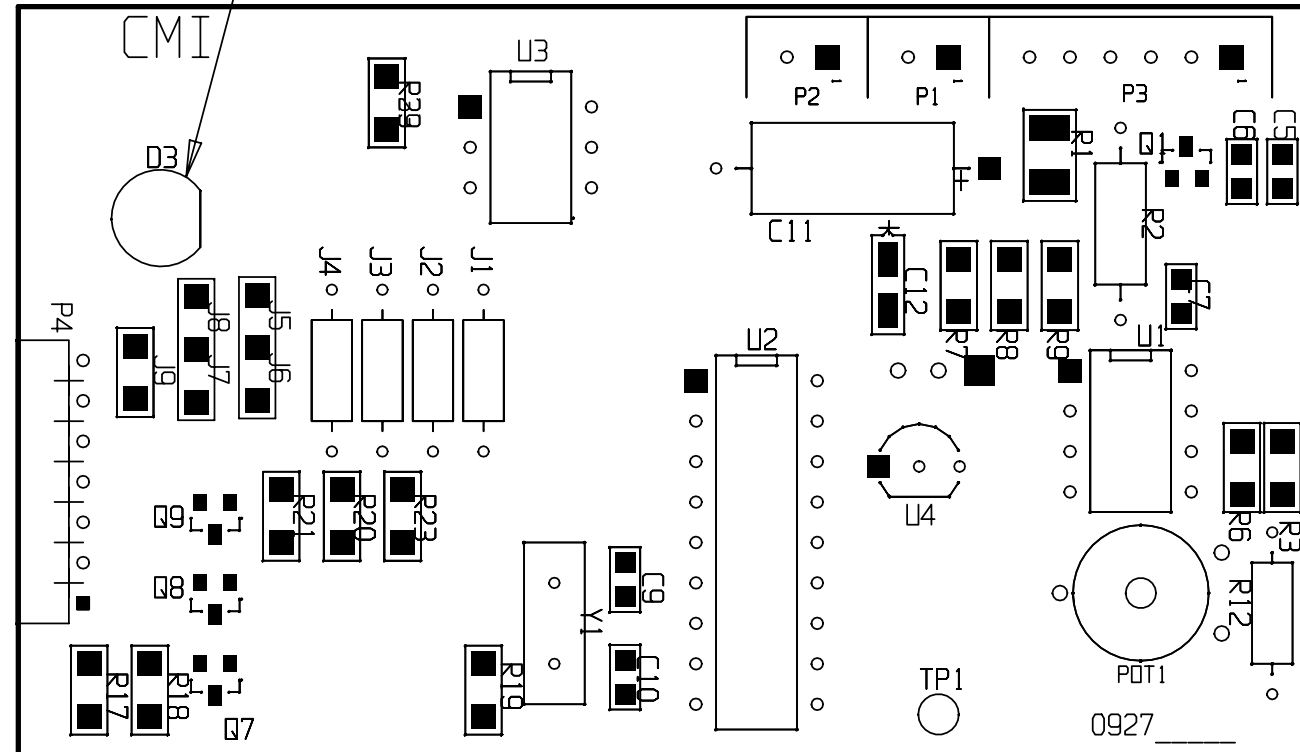
COIN MECHANISMS INC.
400 REGENCY DRIVE
GLENDALE HEIGHTS, IL 60138

TITLE
PCB, CTRL, MC16, 12VDC, S13MS,
SIGMA OPTIC, INH HI, PR14, 7PIN

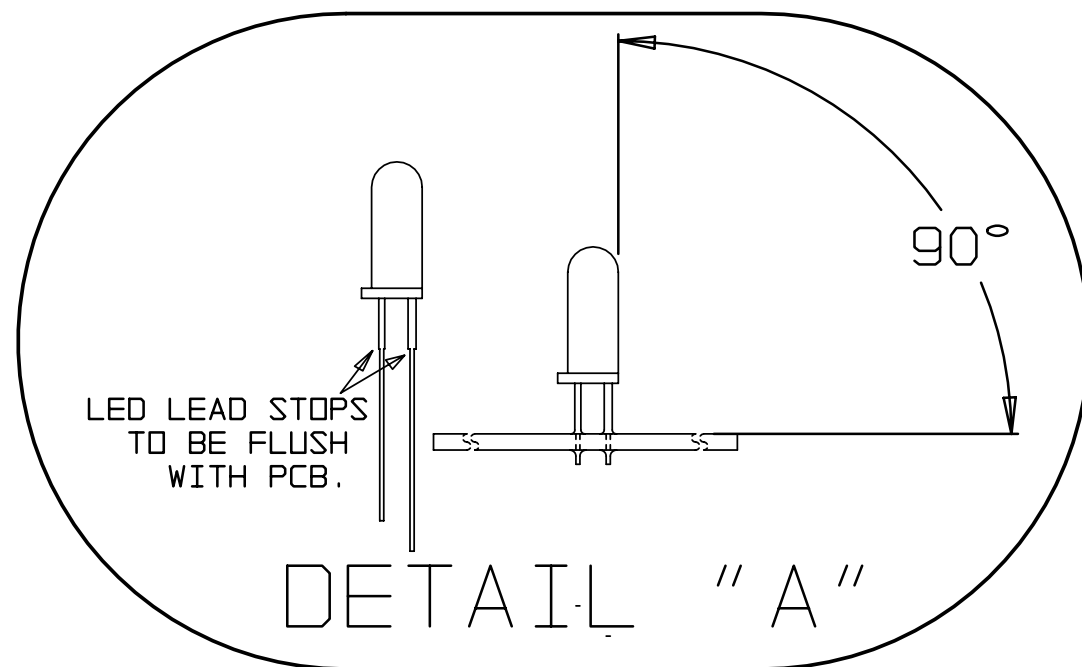
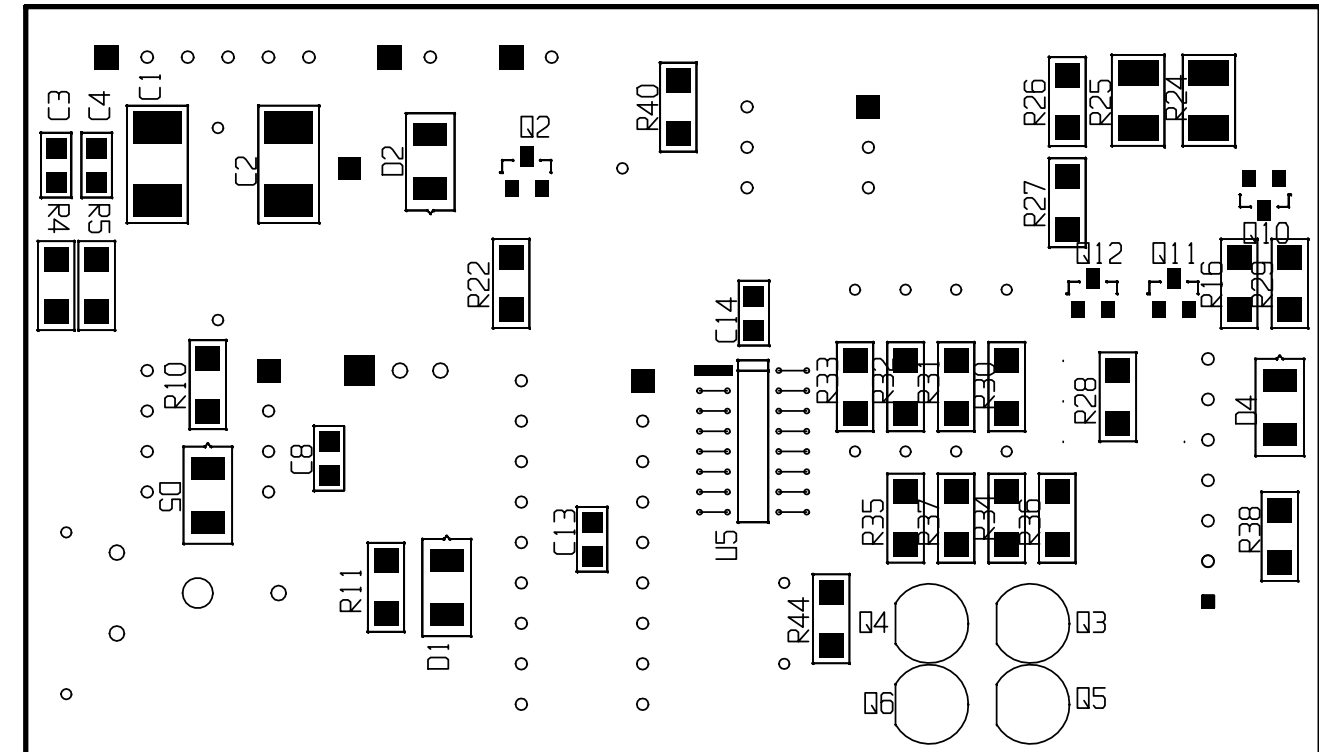
DRAWN BPP **DATE** 5/7/98
APP **DATE**
DWG # 09270287 **REV** 2

SIZE B **SHT** 1 **OF** 3

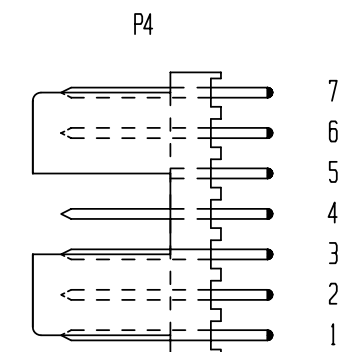
TOP



BOTTOM



1. REFER TO SCHEMATIC DIAGRAM AND PARTS LIST FOR REFERENCE DESIGNATIONS AND COMPONENT VALUES
2. MAXIMUM HEIGHT FOR ANY COMPONENT TO BE .450" EXCEPT FOR LED.
3. MAXIMUM COMPONENT LEAD PROJECTION TO BE .085".
4. SOLDERING SHALL BE IN ACCORDANCE WITH IPC-S-815.
5. ASSEMBLIES TO BE CLEANED OF FLUX AND OTHER CONTAMINANTS AFTER SOLDERING.
6. LEADS TO BE VERTICAL TO PCB DURING SOLDERING PROCESS (SEE DETAIL A).
7. CONNECTORS TO BE FLUSH TO PCB DURING SOLDERING PROCESS.
8. Q3-Q6 MUST BE FLUSH AND PERPENDICULAR TO BOARD.
9. CUT OFF TERMINAL PIN #5 ON P4 FLUSH TO HEADER.



SEE NOTE #9

